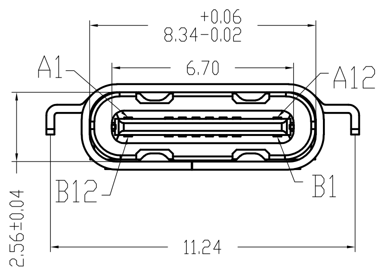
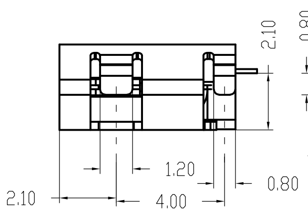
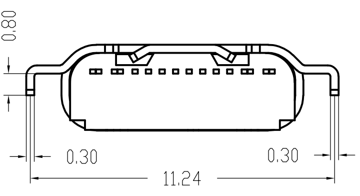
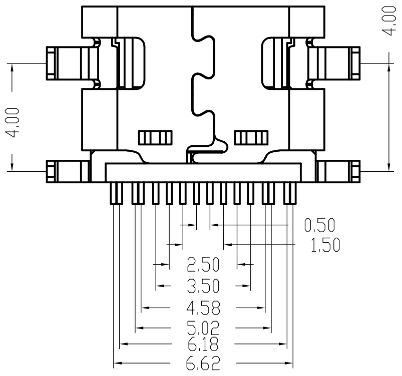
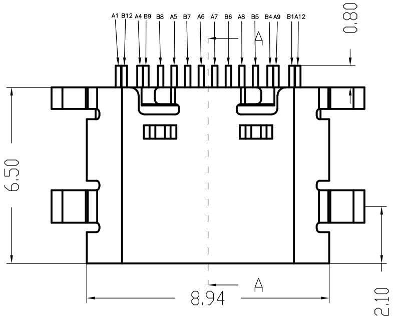
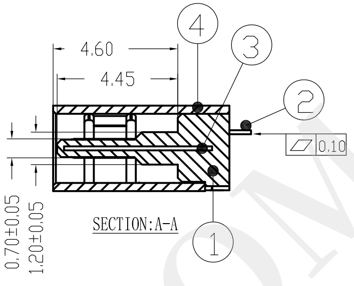


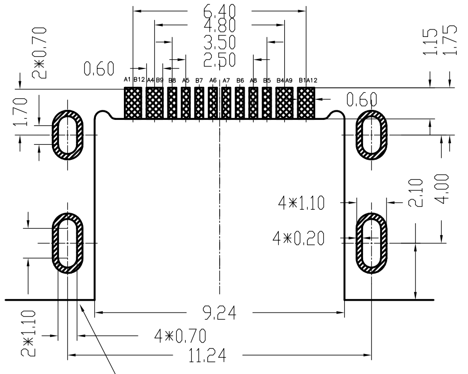






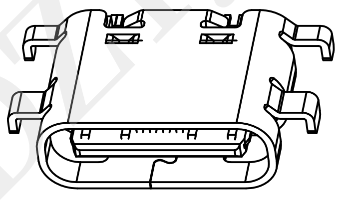






RECOMMENDED PCB LAYOUT(TOP VIEW)

TOLERANCE UNSPECIFIED ±0.05mm



NOTE:

1.MATERIAL SPECIFICATION:
 1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,UL94 V-0.
 2.CONTACTS:COPPER ALLOY
 3.MID PLATE: STAINLESS STEEL
 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:
 2-1.CONTACTS:
  Ni 50u" Min UNDER PLATED OVER ALL.
  Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.
  (GOLD PLATING THICKNESS FOLLOW THE P/N)
  PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 2-2.FRONT SHELL:
  Ni 30u" MIN. UNDER PLATED OVER ALL.
 2-3.SHIELD PLATE&EMI PLATE:
  CLEAR ONLY

3.MECHANICAL PERFORMANCE,
 3-1.INSERTION FORCE: 0.5~2.0kgf.
 3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.
 3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,
 4-1. CURRENT RATING:3.0A(CONTACT MATERIAL IS C2680)
  5.0A(CONTACT MATERIAL IS C7025)
  VOLTAGE RATING:5.0V
 4-2. LLCR:
  VBUS & GND PINS AND OTHER PINS: 40m?/PIN MAX.
  SHIELD: 50m?/MAX.
  LLCR MAX. CHANGE OF ALL PINS: 10m?.
 4-3.INSULATION RESISTANCE: 100M? MIN
 4-4.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:
 OPERATING TEMPERATURE: -25?C~+85?C.

6.IR REFLOW:
 THE PEAK TEMPERATURE ON THE BOARD SHALL
 BE MAINTAINED FOR 10 SECONDS AT 260°C.

USB TYPE-C PIN ASSIGNMENTS

A1	A2	A3	A4	A5	A6	A7	A8	A9	A10	A11	A12
GND	╲	╲	VBUS	CC1	DP1	DN1	SBU1	VBUS	╲	╲	GND
GND	╲	╲	VBUS	SBU2	DN2	DP2	CC2	VBUS	╲	╲	GND
B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1

深圳市华宇创精密电子有限公司

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TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.° ±2° X.X° ±0.5°	DRAWED BY : 陈一鸣	DATE : 2014-02-23	PART NAME: USB TYPE C 母座单排16P SMT沉板2.1
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYC524-USBC16-210 MOLD NO.
UNIT: mm [inch]	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2605271101
SCALE:1:1 SIZE: A4			SHEET NO. 1 OF 1